HALOGEN

FREE

<u>GREEN</u>



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Vishay Semiconductors

High Speed Infrared Emitting Diode, 940 nm, Surface Emitter Technology



LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

As part of the <u>SurfLightTM</u> portfolio, the VSMY2943SLX01 is an infrared, 940 nm, side looking emitting diode based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

• Package type: surface-mount

· Package form: side view

• Dimensions (L x W x H in mm): 2.3 x 2.55 x 2.3

AEC-Q101 qualified

• Peak wavelength: $\lambda_p = 940 \text{ nm}$

High reliability

• High radiant power

• Very high radiant intensity

• Angle of half intensity: $\phi = \pm 28^{\circ}$

· Suitable for high pulse current operation

 Package matches with detector VEMD2xx3SLX01 and VEMT2xx3SLX01 series

• Floor life: 4 weeks, MSL 2a, acc. J-STD-020

 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Automotive sensor
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination
- Remote control
- Head-up displays

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (°)	$\lambda_{\mathbf{p}}$ (nm)	t _r (ns)	
VSMY2943SLX01	50	± 28	940	10	

Note

• Test conditions see table "Basic Characteristics"

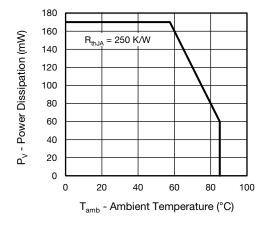
ORDERING INFORMATION					
ORDERING CODE PACKAGING		REMARKS	PACKAGE FORM		
VSMY2943SLX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view		

Note

· MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	5	V
Forward current		I _F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I _{FM}	200	mA
Surge forward current	t _p = 100 μs	I _{FSM}	1	Α
Power dissipation		P_V	180	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	-40 to +85	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	According to Fig. 7, J-STD-020	T _{sd}	260	°C
Thermal resistance junction to ambient	J-STD-051, soldered on PCB	R _{thJA}	250	K/W



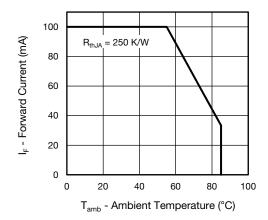


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.4	1.8	V
	$I_F = 1 \text{ A}, t_p = 100 \ \mu\text{s}$	V _F	-	2.5	-	V
Temperature coefficient of V _F	I _F = 100 mA	TK _{VF}	-	-0.7	-	mV/K
Reverse current		I _R	not designed for reverse operation		μA	
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ	-	55	-	pF
Dedicatists with	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	I _e	27	50	75	mW/sr
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e	-	350	-	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe	-	55	-	mW
Temperature coefficient of radiant power	I _F = 100 mA	ΤΚφ _e	-	-0.2	-	%/K
Angle of half intensity		φ	-	± 28	-	0
Peak wavelength	I _F = 100 mA	λ_{p}	920	940	960	nm
Spectral bandwidth	I _F = 100 mA	Δλ	-	50	-	nm
Temperature coefficient of λ_p	I _F = 100 mA	TKλ _p	-	0.25	-	nm/K
Rise time	I _F = 100 mA, 10 % to 90 %	t _r	-	10	-	ns
Fall time	I _F = 100 mA, 10 % to 90 %	t _f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

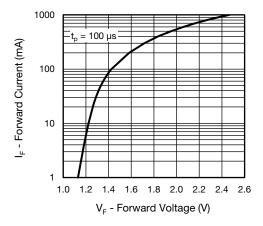


Fig. 3 - Forward Current vs. Forward Voltage

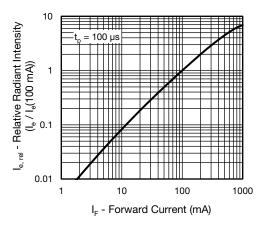


Fig. 4 - Relative Radiant Intensity vs. Forward Current

300 250 255 240 200 Temperature (°C) Max. 30 s 150 Max. 100 s Max. 120 s 100 Max. ramp down 6 °C/s Max. ramp up 3 °C/s 50 50 100 150 200 250

SOLDER PROFILE

19841-1

Time (s) Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

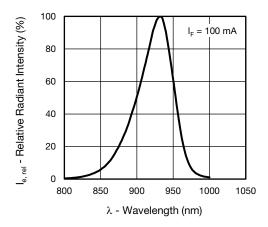


Fig. 5 - Relative Radiant Intensity vs. Wavelength

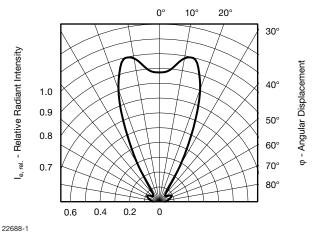


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

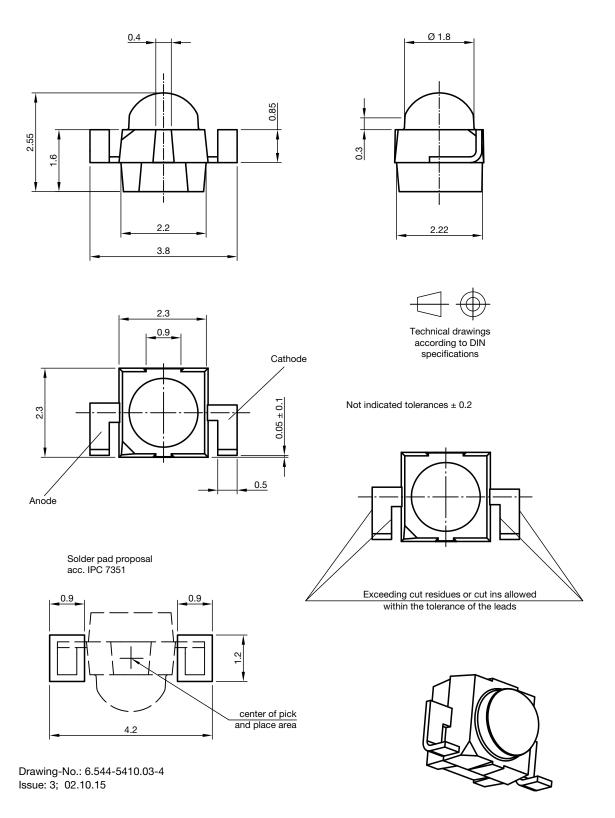
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, according to J-STD-020.

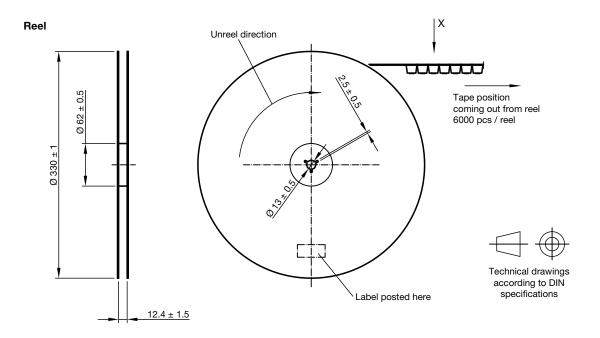
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

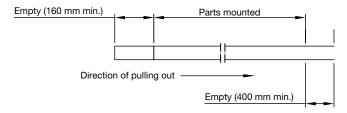
PACKAGE DIMENSIONS in millimeters



TAPING AND REEL DIMENSIONS in millimeters

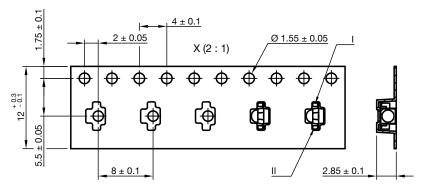


Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II	
VSMB2943SLX01			
VSMF2893SLX01		Anode	
VSMB2948SL	Cathode		
VEMD2023SLX01			
VEMD2523SLX01			
VEMT2023SLX01	Collector	Emitter	
VEMT2523SLX01	Collector		
VSMY2853SL			
VSMY2943SL	Anode	Cathode	
VSMY294310SL			



Drawing-No.: 9.800-5123.01-4

Issue: 4; 02.10.15



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